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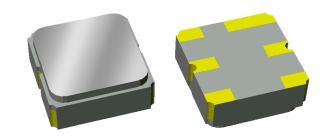
Gnd

Output

Gnd

# **Applications**

- General purpose wireless
- Wireless infrastructure
- **Base Station Applications**



**Functional Block Diagram** 

#### **Product Features**

- Usable bandwidth 65 MHz
- Low loss
- Excellent power handling
- Single-ended operation
- Ceramic Surface Mount Package (SMP)
- Matching required for operation at  $50\Omega$
- Small Size: 3.00 x 3.00 x 1.22 mm
- Hermetically sealed
- RoHS compliant, Pb-free

**Pin Configuration** 

Gnd

Input

Top view

Pin # SE	Description	
2	Input	
5	Output	
1,3,4,6	Case Ground	

#### **General Description**

856992 is a general purpose Uplink filter for Band 25. This filter was specifically designed in a 3x3mm hermetic package for base station applications and is part of our wide portfolio of RF filters in the same package.

Low insertion loss, coupled with high attenuation and excellent power handling, makes this filter a natural choice for our customers' Uplink RF filtering needs.

# Gnd

Pin # SE	Description	
2	Input	
5	Output	
1,3,4,6	Case Ground	

# **Ordering Information**

Part No.	Description
856992	packaged part
960728-EVB	evaluation board
G. 1 1 TE/TO : 5000 :	•

Standard T/R size = 5000 units/reel.

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# **Specifications**

# Electrical Specifications (1)

Specified Temperature Range: (2) -30 to +100 °C

Parameter (3)	Conditions	Min	Typical <sup>(4)</sup>	Max	Units
Center Frequency		-	1882.5	-	MHz
Maximum Insertion Loss	1850 – 1915 MHz	-	1.9	2.5	dB
Amplitude Variation (5)	1850 – 1915 MHz	-	0.3	1.2	dB p-p
Amplitude Variation (5) (over 5 MHz window)	1850 – 1915 MHz	-	0.14	0.8	dB p-p
Temperature Drift <sup>(6)</sup>	1850 – 1915 MHz	-	0.1	0.2	dB
Absolute Group Delay	1850 – 1915 MHz	-	10	15	ns
Group Delay Variation	1850 – 1915 MHz	-	6	15	ns p-p
Phase Ripple	1850 – 1915 MHz	-	14	30	∘ p-p
IIP3 (Tones 5 MHz separated, power > 5 dBm per	1850 – 1915 MHz	44	45	-	dBm
tone)					
EVM (Any 3.84 MHz Channel )	1850 – 1915 MHz	-	0.5	1.0	%
Relative Attenuation (7)	50 – 110 MHz	35	77	-	dB
	300 – 400 MHz	35	55	_	dB
	920 – 965 MHz	35	43	_	dB
	965 – 1300 MHz	25	38	_	dB
	1300 – 1635 MHz	25	34	_	dB
	1635 – 1700 MHz	25	38	_	dB
	1700 – 1790 MHz	10	25	_	dB
	2030 – 2090 MHz	20	32	_	dB
	2560 – 2635 MHz	43	45	_	dB
	4074 – 4162 MHz	20	44	_	dB
	4791 – 4879 MHz	20	36		dB
Input/Output VSWR	1850 – 1915 MHz	-	1.4/1.7	2:0	-
Source Impedance (single-ended) (8)		-	50	-	Ω
Load Impedance (single-ended) (8)		-	50	-	Ω

#### Notes:

- 1. All specifications are based on the TriQuint schematic for the main reference design shown on page 3
- 2. In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature
- 3. Electrical margin has been built into the design to account for the variations due to temperature drift and manufacturing tolerances
- 4. Typical values are based on average measurements at room temperature
- 5. Amplitude Variation is defined as the difference between the lowest loss and the highest loss within defined frequency points
- 6. Temperature Drift specification is defined on Page 3 and is guaranteed by design and won't be measured in production
- 7. Relative to insertion loss at Center Frequency
- 8. This is the optimum impedance in order to achieve the performance shown

### **Absolute Maximum Ratings**

Parameter	Rating
Operable Temperature	-40 to +100 °C
Storage Temperature	-40 to +100 °C
Input Power (9)	+22 dBm

9. Power handling is targeted for an applied CW modulated RF signal at 55 °C for 125 hours

Operation of this device outside the parameter ranges given above may cause permanent damage.

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### **Temperature Drift Specification**

The Definition is:

$$Tempdrift\_hightemp = \frac{\max(T_{25\,deg} - T_{100\,deg}) - \, \min(T_{25\,deg} - \, T_{100\,deg})}{2}$$

$$Tempdrift\_low temp = \frac{\max(T_{25\,deg} - T_{-30\,deg}) - \, \min(T_{25\,deg} - \, T_{-30\,deg})}{2}$$

The Description is:

 $T_{25deg}$  is transmission at 25 degrees in dB.

"Max" and "min" is over frequency.

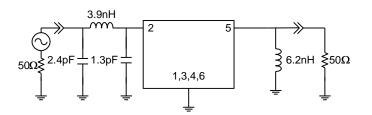
The "temperature drift" is the maximum of

"tempdrift\_lowtemp" and "tempdroft\_hightemp".

# Reference Design $-50\Omega$ SE Input, $50\Omega$ SE Output

#### **Schematic**

50 Ω Single-ended Input

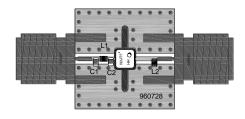


 $\begin{array}{c} 50~\Omega\\ Single-ended\\ Output \end{array}$ 

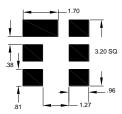
#### Notes:

- 1. Impedance matching is required
- 2. Actual matching values may vary due to PCB layout and parasitic

#### **PC Board**



# **Mounting Configuration**



Notes:

Top, middle & bottom layers: 1/2 oz copper

Substrates: FR4 dielectric .063" / Taconic TLY-5A .0075" Finish plating: Nickel: 3-8µm thick, Gold: .03-.2µm thick

Hole plating: Copper min .0008μm

#### Notes:

- 1. All dimensions are in millimeters.
- 2. This footprint represents a recommendation only.

#### **Bill of Material**

Reference Desg.	Value	Description	Manufacturer	Part Number
L1	3.9nH	Coil wire-wound, 0402, 5%	MuRata	LQW15AN3N9D00
L2	6.2nH	Coil wire-wound, 0402, 5%	MuRata	LQW15AN6N2D00
C1	2.4pF	Chip Capacitor, 0402	MuRata	GRM1555C1H2R4JZ01
C2	1.3pF	Chip Capacitor, 0402	MuRata	GRM1555C1H1R3JZ01
SMA	N/A	SMA connector	Radiall USA Inc.	9602-1111-018
PCB	N/A	3-layer	multiple	960728

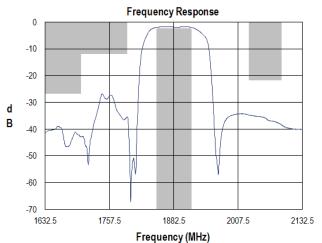
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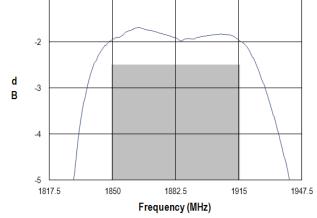
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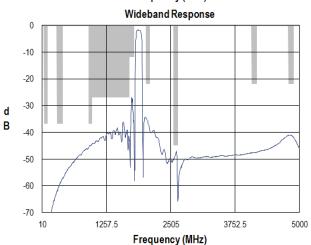
# Typical Performance (at room temperature)

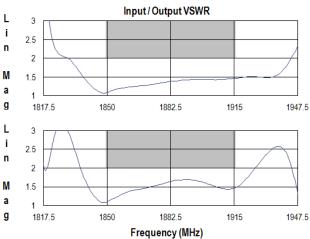


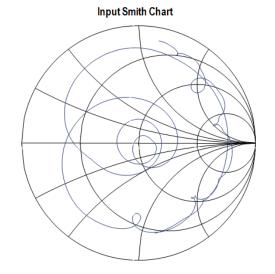


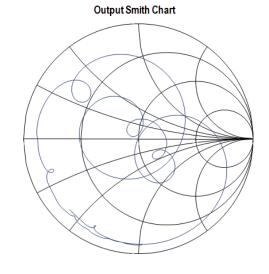
Passband Response

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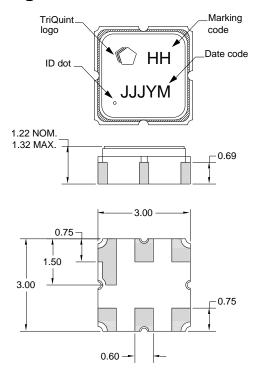
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#### **Mechanical Information**

# **Package Information, Dimensions and Marking**



Package Style: SMP-12A

Dimensions: 3.00 x 3.00 x 1.22 mm

Body:  $Al_2O_3$  ceramic Lid: Kovar, Ni plated

Terminations: Au plating 0.5 - 1.0μm, over a 2-6μm Ni

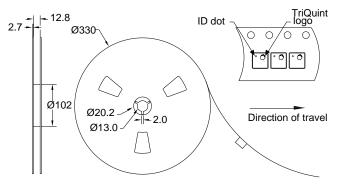
plating

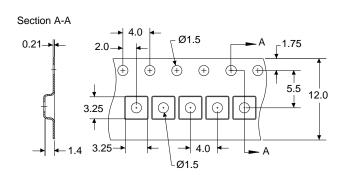
All dimensions shown are nominal in millimeters All tolerances are  $\pm 0.15 mm$  except overall length and width  $\pm 0.10 mm$ 

The date code consists of day of the current year (Julian, 3 digits), Y = last digit of the year, and M = manufacturing site code

### **Tape and Reel Information**

Standard T/R size = 5000 units/reel. All dimensions are in millimeters





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### **Product Compliance Information**

#### **ESD Information**



#### **Caution! ESD-Sensitive Device**

ESD Rating: 1A

Value: Passes  $\geq 300 \text{V min.}$ 

Test: Human Body Model (HBM)
Standard: JEDEC Standard JESD22-A114

ESD Rating: A

Value: Passes  $\geq 150$ V min. Test: Machine Model (MM)

Standard: JEDEC Standard JESD22-A115

### **MSL** Rating

Devices are Hermetic, therefore MSL is not applicable

### **Solderability**

Compatible with the latest version of J-STD-020, lead free solder,  $260^{\circ}\text{C}$ 

Refer to **Soldering Profile** for recommended guidelines.

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A  $(C_{15}H_{12}Br_4O_2)$  Free
- PFOS Free
- SVHC Free

#### **Contact Information**

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about TriQuint:

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